

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4305824

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YAOFENG SUN	03/02/2017
SHA XU	03/02/2017
SHU KIN YAU	03/07/2017
RECEIVING PARTY DATA	
Name:	HONG KONG APPLIED SCIENCE AND TECHNOLOGY RESEARCH INSTITUTE COMPANY LIMITED
Street Address:	5/F, PHOTONICS CENTRE, 2 SCIENCE PARK WEST AVENUE
Internal Address:	HONG KONG SCIENCE PARK, SHATIN, NEW TERRITORIES
City:	HONG KONG
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15451566
CORRESPONDENCE DATA	
Fax Number:	(852)281-0093
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	85228100558
Email:	lodgements.hk@spruson.com
Correspondent Name:	SPRUSON & FERGUSON (HONG KONG) LIMITED
Address Line 1:	5001 HOPEWELL CENTRE
Address Line 2:	183 QUEEN'S ROAD EAST, WAN CHAI
Address Line 4:	HONG KONG, HONG KONG
ATTORNEY DOCKET NUMBER:	P9759US00
NAME OF SUBMITTER:	CHRISTOPHER L. BERNARD
SIGNATURE:	/Christopher L. Bernard/
DATE SIGNED:	03/07/2017
Total Attachments: 2	
source=P9759US00_Assignment#page1.tif	
source=P9759US00_Assignment#page2.tif	

Assignment by Inventors

THIS ASSIGNMENT, made by Yaofeng SUN; Sha XU; Shu Kin YAU (hereinafter referred to as Assignor); residing at

Flat 19, 33/F, Block A, Po Nga Court, Tai Po, Hong Kong;
Flat 5, 21/F, Block E, Fanling Centre, Hong Kong; and
Rm H, 13F, Block 4, The Pinnacle, Junk Bay, Kowloon, Hong Kong respectively.

WHEREAS, Assignor has invented certain new and useful improvements in the patent application entitled Alternate Plating and Etching Processes for Through Hole Filling, set forth in a Patent application for Letters Patent of the United States, filed herewith;

WHEREAS, Hong Kong Applied Science and Technology Research Institute Company Limited, a Limited Liability Company organized under and pursuant to the laws of Hong Kong, China having its principal place of business at 5/F, Photonics Centre, 2 Science Park West Avenue, Hong Kong Science Park, Shatin, New Territories, Hong Kong, China (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said inventions and said Application for Letters Patent of the United States, and in and to any Letters Patent of the United States to be obtained therefore and thereon.

NOW, THEREFORE, for good and sufficient consideration, the receipt of which is hereby acknowledged, Assignor has sold, assigned, transferred and set over, and by these presents do sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to the above-mentioned inventions and application for Letters Patent, and in and to any and all direct and indirect divisions, continuations and continuations-in-part of said application, and any and all Letters Patent in the United States and all foreign countries which may be granted therefore and thereon, and reissues, reexaminations and extensions of said Letters Patent, and all rights under the International Convention for the Protection of Industrial Property, the same to be held and enjoyed by Assignee, for its own use and benefit and the use and benefit of its successors, legal representatives and assigns, to the full end of the term or terms for which Letters Patent may be granted and/or extended, as fully and entirely as the same would have been held and enjoyed by Assignor, had this sale and assignment not been made.

AND for the same consideration, Assignor hereby represent and warrant to Assignee, its successors, legal representatives and assigns, that, at the time of execution and delivery of these presents, except for any rights, titles and/or interests that have arisen to Assignee under law or that have already been transferred to Assignee, Assignor is the sole and lawful owners of the entire right, title and interest in and to the said inventions and application for Letters Patent above-mentioned, and that the same are unencumbered and that Assignor has good and full right and lawful authority to sell and convey the same in the manner herein set forth.

AND for the same consideration, Assignor hereby covenant and agree to and with Assignee, its successors, legal representatives and assigns, that Assignor will sign all papers and documents, take all lawful oaths and do all acts necessary or required to be done for the procurement, maintenance, enforcement and defense of any Letters Patent and applications for Letters Patent for said inventions, whenever counsel of Assignee, or counsel of its successors, legal representatives and assigns, shall advise: that any proceeding in connection with said inventions, or said Patent application for Letters Patent, or any proceeding in connection with any Letters Patent or applications for Letters Patent for said inventions in any country, including but not limited to interference proceedings, is lawful and desirable; or, that any division, continuation or continuation-in-part of any application for Letters Patent, or any reissue, reexamination or extension of any Letters Patent, to be obtained thereon, is lawful and desirable.

AND Assignor hereby request the Commissioner of Patent and Trademarks to issue said Letters Patent of the United States to Assignee, as Assignee of said inventions and the Letters Patent to be issued thereon, for the sole use and benefit of Assignee, its successors, legal representatives and assigns.

AND Assignor hereby grant the following the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document:

Spruson & Ferguson (Hong Kong) Limited

and all practitioners at Customer Number: 95527

AND Assignor acknowledge an obligation of assignment of this invention to Assignee at the time the invention was made.

Date: 2/3/2017


Yaofeng SUN

Date: 2/3/2017


Sha XU

Date: 7/3/2017


Shu Kin YAU